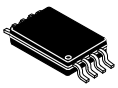
EEPROM Serial 2-Kb I²C for DDR2 DIMM SPD

CAT34C02



TSSOP−8
Y SUFFIX
CASE 948AL



TDFN−8
VP2 SUFFIX
CASE 511AK



UDFN−8 EP
HU4 SUFFIX
CASE 517AZ

Description

The CAT34C02 is a EEPROM Serial 2−Kb I²C, internally organized as 16 pages of 16 bytes each, for a total of 256 bytes of 8 bits each.

It features a 16−byte page write buffer and supports both the Standard (100 kHz) as well as Fast (400 kHz) I²C protocol.

Write operations can be inhibited by taking the WP pin High (this protects the entire memory) or by setting an internal Write Protect flag via Software command (this protects the lower half of the memory).

In addition to Permanent Software Write Protection, the CAT34C02 also features JEDEC compatible Reversible Software Write Protection for DDR2 Serial Presence Detect (SPD) applications operating over the 1.7 V to 3.6 V supply voltage range.

The CAT34C02 is fully backwards compatible with earlier DDR1 SPD applications operating over the 1.7 V to 5.5 V supply voltage range.

Features

- Supports Standard and Fast I²C Protocol
- 1.7 V to 5.5 V Supply Voltage Range
- 16−Byte Page Write Buffer
- Hardware Write Protection for Entire Memory
- Software Write Protection for Lower 128 Bytes
- Schmitt Triggers and Noise Suppression Filters on I²C Bus Inputs (SCL and SDA)
- Low power CMOS Technology
- 1,000,000 Program/Erase Cycles
- 100 Year Data Retention
- Industrial and Extended Temperature Range
- This Device is Pb−Free, Halogen Free/BFR Free and RoHS Compliant*

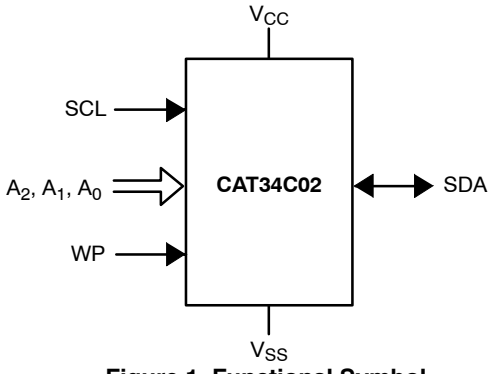
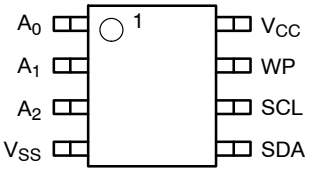


Figure 1. Functional Symbol

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PIN CONFIGURATION



TSSOP (Y), TDFN (VP2),
UDFN (HU4)

For the location of Pin 1, please consult the corresponding package drawing.

PIN FUNCTION

Pin Name	Function
A_0, A_1, A_2	Device Address Input
SDA	Serial Data Input/Output
SCL	Serial Clock Input
WP	Write Protect Input
V_{CC}	Power Supply
V_{SS}	Ground

ORDERING INFORMATION

See detailed ordering and shipping information in page 10 of this data sheet.

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Table 1. ABSOLUTE MAXIMUM RATINGS

Parameter	Rating	Unit
Operating Temperature	−45 to +130	°C
Storage Temperature	−65 to +150	°C
Voltage on Any Pin with Respect to Ground (Note 1)	−0.5 to +6.5	V
Voltage on Pin A_0 with Respect to Ground	−0.5 to +10.5	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The DC input voltage on any pin should not be lower than −0.5 V. During transitions, the voltage on any pin may undershoot to no less than −1.5 V, for periods of less than 20 ns.

Table 2. RELIABILITY CHARACTERISTICS (Note 2)

Symbol	Parameter	Min	Units
N_{END} (Note 3)	Endurance	1,000,000	Program/ Erase Cycles
T_{DR}	Data Retention	100	Years

2. These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC−Q100 and JEDEC test methods.
3. Page Mode, V_{CC} = 5 V, 25°C

Table 3. D.C. OPERATING CHARACTERISTICS
(V_{CC} = 1.7 V to 5.5 V, T_A = −40°C to +85°C and V_{CC} = 2.5 V to 5.5 V, T_A = −40°C to +125°C, unless otherwise specified.)

Symbol	Parameter	Test Conditions		Min	Max	Units
I_{CC}	Supply Current	V_{CC} < 3.6 V, f_{SCL} = 100 kHz			1	mA
		V_{CC} > 3.6 V, f_{SCL} = 400 kHz			2	
I_{SB}	Standby Current	All I/O Pins at GND or V_{CC}	T_A = −40°C to +85°C V_{CC} ≤ 3.3 V		1	μA
			T_A = −40°C to +85°C V_{CC} > 3.3 V		3	
			T_A = −40°C to +125°C		5	
I_L	I/O Pin Leakage	Pin at GND or V_{CC}			2	μA
V_{IL}	Input Low Voltage			−0.5	0.3 x V_{CC}	V
V_{IH}	Input High Voltage			0.7 x V_{CC}	V_{CC} + 0.5*	
V_{OL}	Output Low Voltage	V_{CC} > 2.5 V, I_{OL} = 3 mA			0.4	
		V_{CC} < 2.5 V, I_{OL} = 1 mA			0.2	

*V_{IH} Max = 4 V for SDA and SCL when V_{CC} = 0 V.

Table 4. PIN IMPEDANCE CHARACTERISTICS
(V_{CC} = 1.7 V to 5.5 V, T_A = −40°C to +85°C and V_{CC} = 2.5 V to 5.5 V, T_A = −40°C to +125°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Max	Units
C_{IN} (Note 4)	SDA I/O Pin Capacitance	V_{IN} = 0 V, f = 1.0 MHz, V_{CC} = 5.0 V	8	pF
	Other Input Pins		6	
I_{WP} (Note 5)	WP Input Current	V_{IN} < V_{IH}, V_{CC} = 5.5 V	130	μA
		V_{IN} < V_{IH}, V_{CC} = 3.6 V	120	
		V_{IN} < V_{IH}, V_{CC} = 1.7 V	80	
		V_{IN} > V_{IH}	2	
I_A (Note 5)	Address Input Current (A0, A1, A2) Product Rev H	V_{IN} < V_{IH}, V_{CC} = 5.5 V	50	μA
		V_{IN} < V_{IH}, V_{CC} = 3.6 V	35	
		V_{IN} < V_{IH}, V_{CC} = 1.7 V	25	
		V_{IN} > V_{IH}	2	

4. These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC−Q100 and JEDEC test methods.
5. When not driven, the WP, A0, A1 and A2 pins are pulled down to GND internally. For improved noise immunity, the internal pull−down is relatively strong; therefore the external driver must be able to supply the pull−down current when attempting to drive the input HIGH. To conserve power, as the input level exceeds the trip point of the CMOS input buffer (~ 0.5 x V_{CC}), the strong pull−down reverts to a weak current source.

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Table 5. A.C. CHARACTERISTICS
(V_{CC} = 1.7 V to 5.5 V, T_A = −40°C to +85°C and V_{CC} = 2.5 V to 5.5 V, T_A = −40°C to +125°C) (Note 6)

Symbol	Parameter	Standard		Fast		Units
		Min	Max	Min	Max	
F_{SCL}	Clock Frequency		100		400	kHz
$t_{HD:STA}$	START Condition Hold Time	4		0.6		μs
t_{LOW}	Low Period of SCL Clock	4.7		1.3		μs
t_{HIGH}	High Period of SCL Clock	4		0.6		μs
$t_{SU:STA}$	START Condition Setup Time	4.7		0.6		μs
$t_{HD:DAT}$	Data Hold Time	0		0		μs
$t_{SU:DAT}$	Data Setup Time	250		100		ns
t_R (Note 7)	SDA and SCL Rise Time		1000		300	ns
t_F (Note 7)	SDA and SCL Fall Time		300		300	ns
$t_{SU:STO}$	STOP Condition Setup Time	4		0.6		μs
t_{BUF}	Bus Free Time Between STOP and START	4.7		1.3		μs
t_{AA}	SCL Low to SDA Data Out		3.5		0.9	μs
t_{DH}	Data Out Hold Time	100		100		ns
T_i (Note 7)	Noise Pulse Filtered at SCL and SDA Inputs		100		100	ns
$t_{SU:WP}$	WP Setup Time	0		0		μs
$t_{HD:WP}$	WP Hold Time	2.5		2.5		μs
t_{WR}	Write Cycle Time		5		5	ms
t_{PU} (Notes 7 & 8)	Power−up to Ready Mode		1		1	ms

6. Test conditions according to “A.C. Test Conditions” table.
7. Tested initially and after a design or process change that affects this parameter.
8. t_{PU} is the delay between the time V_{CC} is stable and the device is ready to accept commands.

Table 6. THERMAL CHARACTERISTICS (Air velocity = 0 m/s, 4 layers PCB) (Notes 9 and 10)

Part Number	Package	θ_{JA}	θ_{JC}	Units
CAT34C02Y	TSSOP	64	37	°C/W
CAT34C02VP2	TDFN	92	15	°C/W
CAT34C02HU3	UDFN	101	18	°C/W
CAT34C02HU4	UDFN	101	18	°C/W

9. $T_J = T_A + P_D * \theta_{JA}$, where: T_J is the Junction Temperature, T_A the Ambient Temperature, P_D the Power dissipation.
   Example: CAT34C02VP2, V_{CC} = 3.0 V, I_{CCmax} = 1 mA, T_A = 85°C: T_J = 85°C + 3 mW * 92°C/W = 85.276°C.
10. $T_J = T_C + P_D * \theta_{JC}$, where: T_C is the Case Temperature, etc.

Table 7. A.C. TEST CONDITIONS

Input Levels	0.2 V_{CC} to 0.8 V_{CC}
Input Rise and Fall Times	≤ 50 ns
Input Reference Levels	0.3 V_{CC}, 0.7 V_{CC}
Output Reference Levels	0.5 V_{CC}
Output Load	Current Source: I_{OL} = 3 mA (V_{CC} ≥ 2.5 V); I_{OL} = 1 mA (V_{CC} < 2.5 V); C_L = 100 pF

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POWER−ON RESET (POR)

The CAT34C02 incorporates Power−On Reset (POR) circuitry which protects the internal logic against powering up in the wrong state.

The CAT34C02 will power up into Standby mode after V_{CC} exceeds the POR trigger level and will power down into Reset mode when V_{CC} drops below the POR trigger level. This bi−directional POR feature protects the device against 'brown−out' failure following a temporary loss of power.

PIN DESCRIPTION

SCL: The Serial Clock input pin accepts the Serial Clock generated by the Master.

SDA: The Serial Data I/O pin receives input data and transmits data stored in EEPROM. In transmit mode, this pin is open drain. Data is acquired on the positive edge, and is delivered on the negative edge of SCL.

A_0, A_1 and A_2: The Address pins accept the device address. These pins have on−chip pull−down resistors.

WP: The Write Protect input pin inhibits all write operations, when pulled HIGH. This pin has an on−chip pull−down resistor.

FUNCTIONAL DESCRIPTION

The CAT34C02 supports the Inter−Integrated Circuit (I^2C) Bus data transmission protocol, which defines a device that sends data to the bus as a transmitter and a device receiving data as a receiver. Data flow is controlled by a Master device, which generates the serial clock and all START and STOP conditions. The CAT34C02 acts as a Slave device. Master and Slave alternate as either transmitter or receiver. Up to 8 devices may be connected to the bus as determined by the device address inputs A_0, A_1, and A_2.

I^2C BUS PROTOCOL

The I^2C bus consists of two 'wires', SCL and SDA. The two wires are connected to the V_{CC} supply via pull−up resistors. Master and Slave devices connect to the 2−wire bus via their respective SCL and SDA pins. The transmitting device pulls down the SDA line to 'transmit' a '0' and releases it to 'transmit' a '1'.

Data transfer may be initiated only when the bus is not busy (see A.C. Characteristics).

During data transfer, the SDA line must remain stable while the SCL line is HIGH. An SDA transition while SCL is HIGH will be interpreted as a START or STOP condition (Figure 2).

Start

The START condition precedes all commands. It consists of a HIGH to LOW transition on SDA while SCL is HIGH. The START acts as a 'wake−up' call to all receivers. Absent a START, a Slave will not respond to commands.

Stop

The STOP condition completes all commands. It consists of a LOW to HIGH transition on SDA while SCL is HIGH. The STOP starts the internal Write cycle (when following a Write command) or sends the Slave into standby mode (when following a Read command).

Device Addressing

The Master initiates data transfer by creating a START condition on the bus. The Master then broadcasts an 8−bit serial Slave address. The first 4 bits of the Slave address are set to 1010, for normal Read/Write operations (Figure 3). The next 3 bits, A_2, A_1 and A_0, select one of 8 possible Slave devices. The last bit, R/$\overline{W}$, specifies whether a Read (1) or Write (0) operation is to be performed.

Acknowledge

After processing the Slave address, the Slave responds with an acknowledge (ACK) by pulling down the SDA line during the 9^{th} clock cycle (Figure 4). The Slave will also acknowledge the byte address and every data byte presented in Write mode. In Read mode the Slave shifts out a data byte, and then releases the SDA line during the 9^{th} clock cycle. If the Master acknowledges the data, then the Slave continues transmitting. The Master terminates the session by not acknowledging the last data byte (NoACK) and by sending a STOP to the Slave. Bus timing is illustrated in Figure 5.

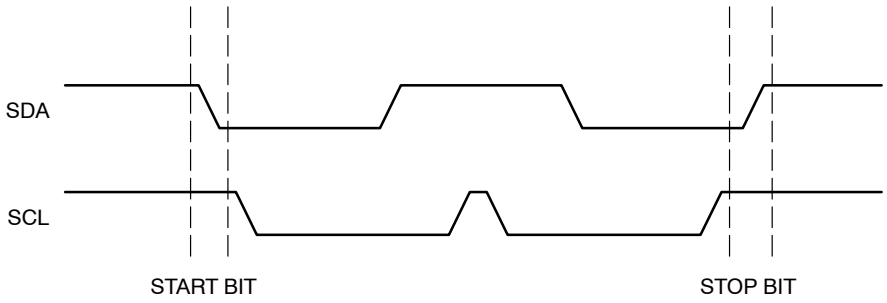


Figure 2. Start/Stop Timing

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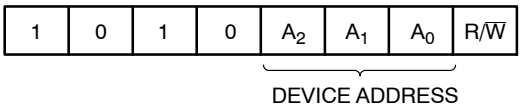


Figure 3. Slave Address Bits

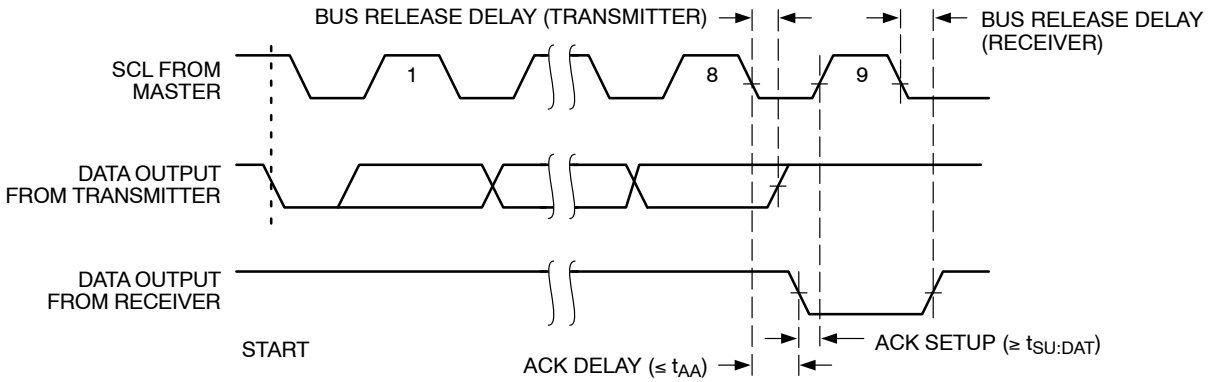


Figure 4. Acknowledge Timing

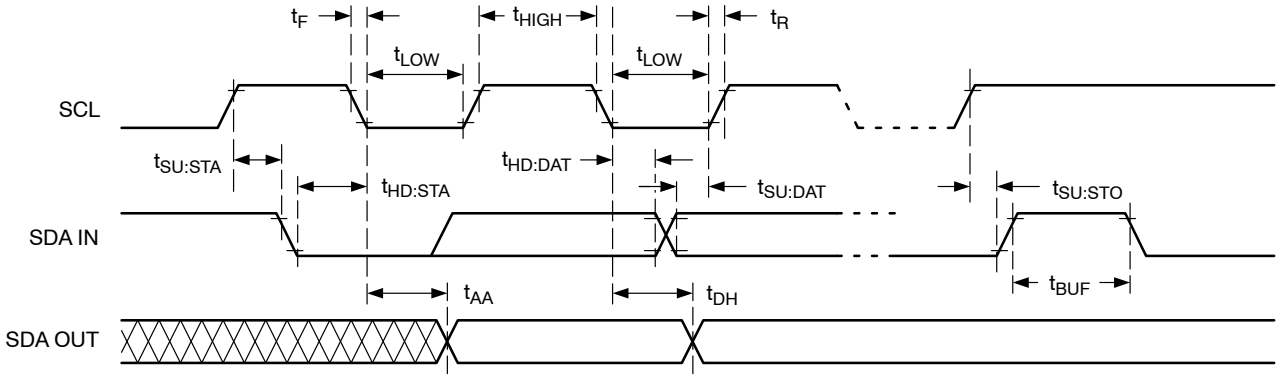


Figure 5. Bus Timing

WRITE OPERATIONS

Byte Write

In Byte Write mode the Master sends a START, followed by Slave address, byte address and data to be written (Figure 6). The Slave acknowledges all 3 bytes, and the Master then follows up with a STOP, which in turn starts the internal Write operation (Figure 7). During internal Write, the Slave will not acknowledge any Read or Write request from the Master.

Page Write

The CAT34C02 contains 256 bytes of data, arranged in 16 pages of 16 bytes each. A page is selected by the 4 most significant bits of the address byte following the Slave address, while the 4 least significant bits point to the byte within the page. Up to 16 bytes can be written in one Write cycle (Figure 8).

The internal byte address counter is automatically incremented after each data byte is loaded. If the Master transmits more than 16 data bytes, then earlier bytes will be overwritten by later bytes in a ‘wrap−around’ fashion (within the selected page). The internal Write cycle starts immediately following the STOP.

Acknowledge Polling

Acknowledge polling can be used to determine if the CAT34C02 is busy writing or is ready to accept commands. Polling is implemented by interrogating the device with a ‘Selective Read’ command (see READ OPERATIONS).

The CAT34C02 will not acknowledge the Slave address, as long as internal Write is in progress.

DELIVERY STATE

The CAT34C02 is shipped ‘unprotected’, i.e. neither SWP flag is set. The entire 2 kb memory is erased, i.e. all bytes are FFh.

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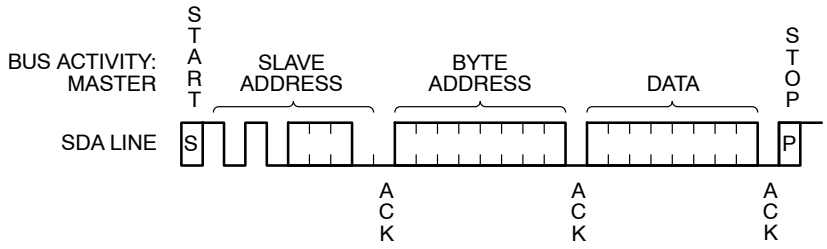


Figure 6. Byte Write Timing

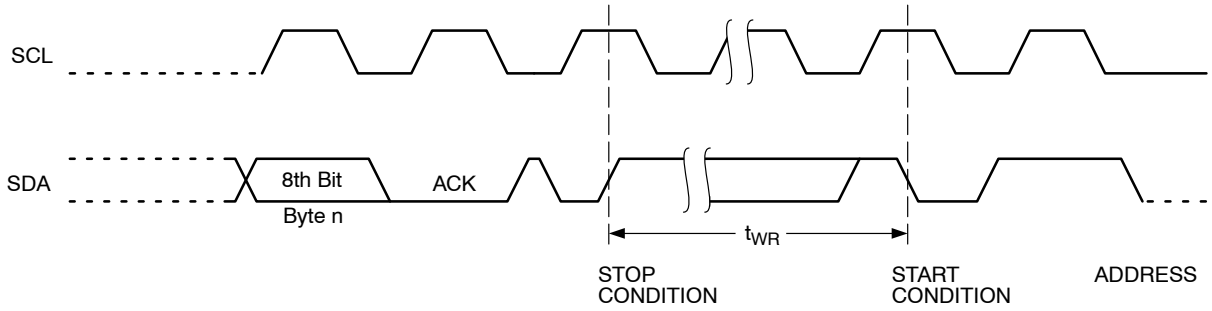
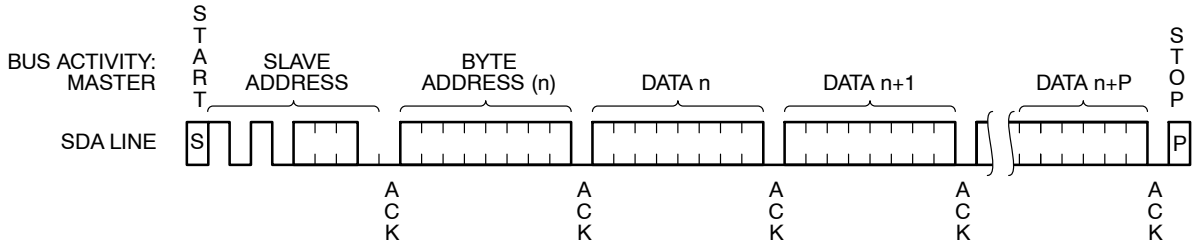


Figure 7. Write Cycle Timing



NOTE: IN THIS EXAMPLE n = XXXX 0000(B); X = 1 or 0

Figure 8. Page Write Timing

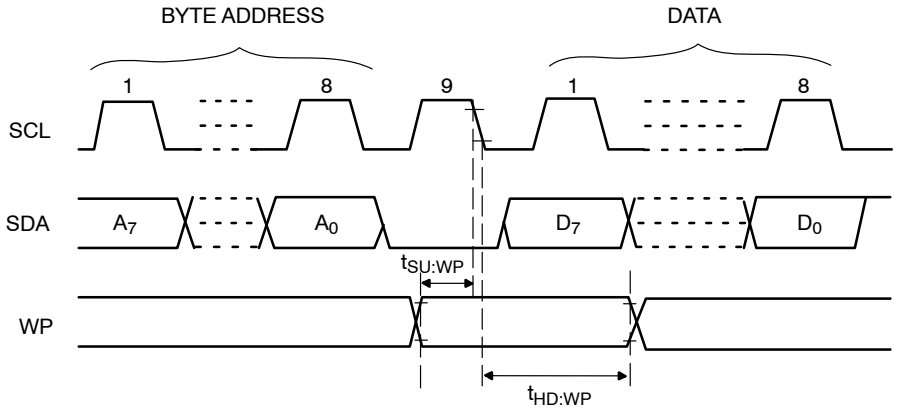


Figure 9. WP Timing

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READ OPERATIONS

Immediate Address Read

In standby mode, the CAT34C02 internal address counter points to the data byte immediately following the last byte accessed by a previous operation. If that 'previous' byte was the last byte in memory, then the address counter will point to the 1st memory byte, etc.

When, following a START, the CAT34C02 is presented with a Slave address containing a '1' in the R/$\overline{W}$ bit position (Figure 10), it will acknowledge (ACK) in the 9th clock cycle, and will then transmit data being pointed at by the internal address counter. The Master can stop further transmission by issuing a NoACK, followed by a STOP condition.

Selective Read

The Read operation can also be started at an address different from the one stored in the internal address counter. The address counter can be initialized by performing a 'dummy' Write operation (Figure 11). Here the START is followed by the Slave address (with the R/$\overline{W}$ bit set to '0') and the desired byte address. Instead of following up with data, the Master then issues a 2nd START, followed by the 'Immediate Address Read' sequence, as described earlier.

Sequential Read

If the Master acknowledges the 1st data byte transmitted by the CAT34C02, then the device will continue transmitting as long as each data byte is acknowledged by the Master (Figure 12). If the end of memory is reached during sequential Read, then the address counter will 'wrap−around' to the beginning of memory, etc. Sequential Read works with either 'Immediate Address Read' or 'Selective Read', the only difference being the starting byte address.

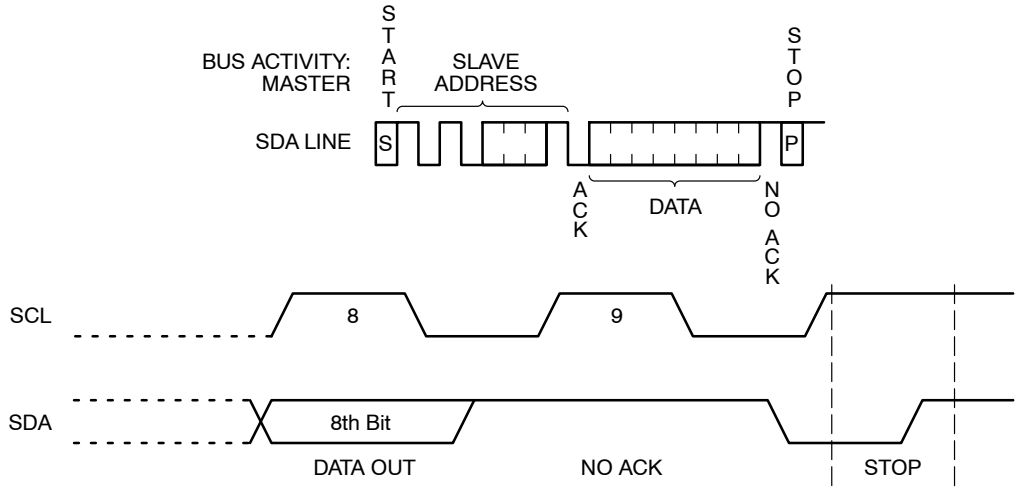


Figure 10. Immediate Address Read Timing

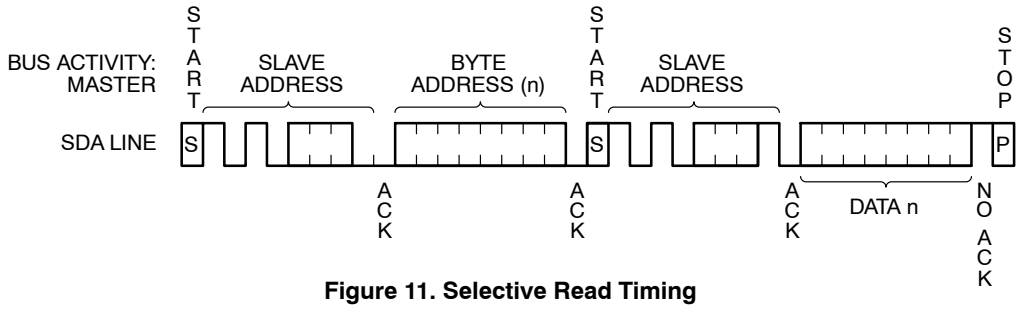


Figure 11. Selective Read Timing

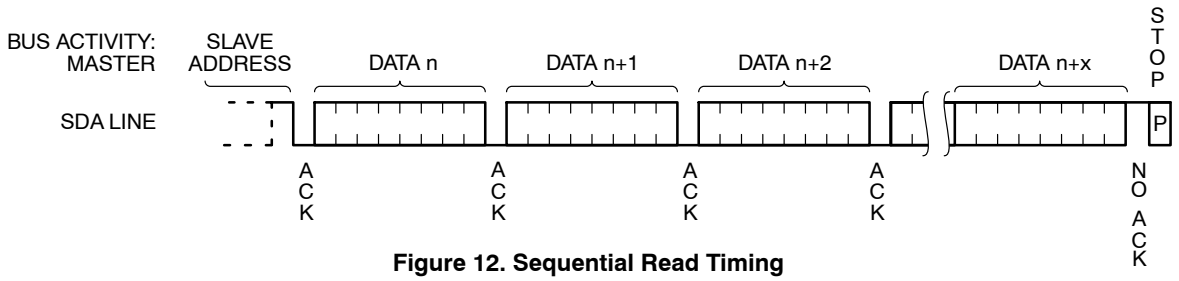


Figure 12. Sequential Read Timing

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SOFTWARE WRITE PROTECTION

The lower half of memory (first 128 bytes) can be protected against Write requests by setting one of two Software Write Protection (SWP) flags.

The Permanent Software Write Protection (PSWP) flag can be set or read while all address pins are at regular CMOS levels (GND or V_{CC}), whereas the very high voltage V_{HV} must be present on address pin A_0 to set, clear or read the Reversible Software Write Protection (**RSWP**) flag. The D.C. OPERATING CONDITIONS for RSWP operations are shown in Table 8.

The SWP commands are listed in Table 9. All commands are preceded by a START and terminated with a STOP, following the ACK or NoACK from the CAT34C02. All SWP related Slave addresses use the pre−amble: 0110 (6h), instead of the regular 1010 (Ah) used for memory access. For **PSWP** commands, the three address pins can be at any logic level, whereas for **RSWP** commands the address pins must be at pre−assigned logic levels. V_{HV} is interpreted as logic '1'. The V_{HV} condition must be established on pin A_0 before the START and maintained just beyond the STOP. Otherwise an RSWP request could be interpreted by the CAT34C02 as a PSWP request.

The SWP Slave addresses follow the standard I^2C convention, i.e. to read the state of the SWP flag, the LSB of the Slave address must be '1', and to set or clear a flag, it must be '0'. For Write commands a dummy byte address and dummy data byte must be provided (Figure 14). In contrast to a regular memory Read, a SWP Read does not return Data. Instead the CAT34C02 will respond with NoACK if the flag is set and with ACK if the flag is not set. Therefore, the Master can immediately follow up with a STOP, as there is no meaningful data following the ACK interval (Figure 15).

HARDWARE WRITE PROTECTION

With the WP pin held HIGH, the entire memory, as well as the SWP flags are protected against Write operations, see Memory Protection Map below. If the WP pin is left floating or is grounded, it has no impact on the operation of the CAT34C02.

The state of the WP pin is strobed on the last falling edge of SCL immediately preceding the first data byte (Figure 9). If the WP pin is HIGH during the strobe interval, the CAT34C02 will not acknowledge the data byte and the Write request will be rejected.

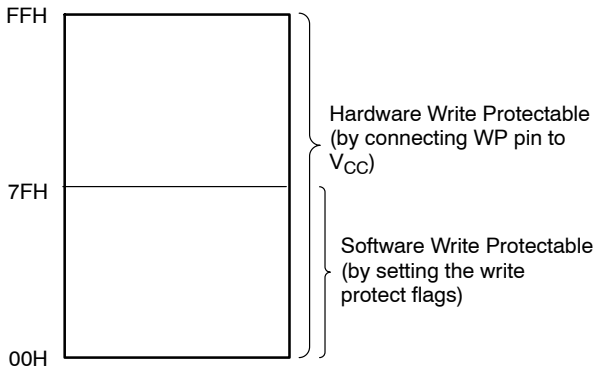


Figure 13. Memory Protection Map

Table 8. RSWP D.C. OPERATING CONDITIONS (Note 11)

Symbol	Parameter	Test Conditions	Min	Max	Units
ΔV_{HV}	A_0 Overdrive (V_{HV} − V_{CC})	1.7 V < V_{CC} < 3.6 V	4.8		V
I_{HVD}	A_0 High Voltage Detector Current			0.1	mA
V_{HV}	A_0 Very High Voltage		7	10	V
I_{HV}	A_0 Input Current @ V_{HV}			1	mA

11. To prevent damaging the CAT34C02 while applying V_{HV}, it is strongly recommended to limit the power delivered to pin A_0, by inserting a series resistor (> 1.5 kΩ) between the supply and the input pin. The resistance is only limited by the combination of V_{HV} and maximum I_{HVD}. While the resistor can be omitted if V_{HV} is clamped well below 10 V, it nevertheless provides simple protection against EOS events.
As an example: V_{CC} = 1.7 V, V_{HV} = 8 V, 1.5 kΩ < R_S < 15 kΩ.

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Table 9. SWP COMMANDS

Action	Control Pin Levels (Note 12)				Flag State (Note 13)		Slave Address					ACK ?	Address Byte	ACK ?	Data Byte	ACK ?	Write Cycle
	WP	A_2	A_1	A_0	PSWP	RSWP	b_7 to b_4	b_3	b_2	b_1	b_0						
Set PSWP	X	A_2	A_1	A_0	1	X	0110	A_2	A_1	A_0	X	No					
	GND	A_2	A_1	A_0	0	X		A_2	A_1	A_0	0	Yes	X	Yes	X	Yes	Yes
	V_{CC}	A_2	A_1	A_0	0	X		A_2	A_1	A_0	0	Yes	X	Yes	X	No	No
	X	A_2	A_1	A_0	0	X		A_2	A_1	A_0	1	Yes					
Set RSWP	X	GND	GND	V_{HV}	1	X		0	0	1	X	No					
	X	GND	GND	V_{HV}	0	1		0	0	1	X	No					
	GND	GND	GND	V_{HV}	0	0		0	0	1	0	Yes	X	Yes	X	Yes	Yes
	V_{CC}	GND	GND	V_{HV}	0	0		0	0	1	0	Yes	X	Yes	X	No	No
	X	GND	GND	V_{HV}	0	0		0	0	1	1	Yes					
Clear RSWP	X	GND	V_{CC}	V_{HV}	1	X		0	1	1	X	No					
	GND	GND	V_{CC}	V_{HV}	0	X		0	1	1	0	Yes	X	Yes	X	Yes	Yes
	V_{CC}	GND	V_{CC}	V_{HV}	0	X		0	1	1	0	Yes	X	Yes	X	No	No
	X	GND	V_{CC}	V_{HV}	0	X		0	1	1	1	Yes					

12. Here A_2, A_1 and A_0 are either at V_{CC} or GND.
13. 1 stands for 'Set', 0 stands for 'Not Set', X stands for 'don't care'.

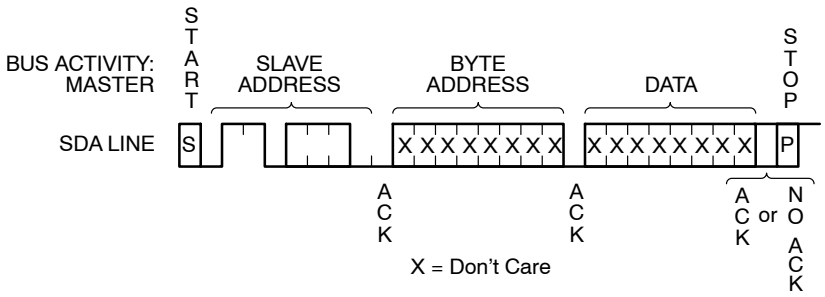


Figure 14. Software Write Protect (Write)

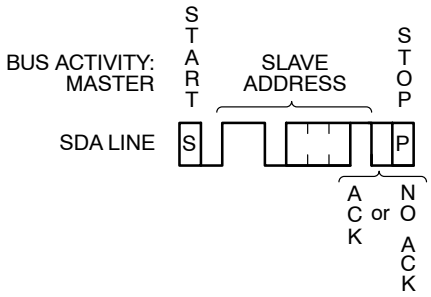


Figure 15. Software Write Protect (Read)

Share Feedback
Your Opinion Matters

ORDERING INFORMATION

Device Order Number	Specific Device Marking	Package Type	Temperature Range	Lead Finish	Shipping†
CAT34C02HU4EGT4A	D1U	UDFN−8	I = Industrial (−40°C to +85°C)	NiPdAu	Tape & Reel, 4,000 Units / Reel
CAT34C02HU4I−GT4	D1U	UDFN−8	I = Industrial (−40°C to +85°C)	NiPdAu	Tape & Reel, 4,000 Units / Reel
CAT34C02HU4I−GTK	D1U	UDFN−8	I = Industrial (−40°C to +85°C)	NiPdAu	Tape & Reel, 4,000 Units / Reel
CAT34C02HU4IGT4A	D1U	UDFN−8	I = Industrial (−40°C to +85°C)	NiPdAu	Tape & Reel, 4,000 Units / Reel
CAT34C02HU4IGT4U5	D1U	UDFN−8	I = Industrial (−40°C to +85°C)	NiPdAu	Tape & Reel, 4,000 Units / Reel
CAT34C02VP2I−GT4	D1T	TDFN−8	I = Industrial (−40°C to +85°C)	NiPdAu	Tape & Reel, 4,000 Units / Reel
CAT34C02VP2IGT4A	D1T	TDFN−8	I = Industrial (−40°C to +85°C)	NiPdAu	Tape & Reel, 4,000 Units / Reel
CAT34C02YI−GT5	34CH	TSSOP−8	I = Industrial (−40°C to +85°C)	NiPdAu	Tape & Reel, 5,000 Units / Reel
CAT34C02YI−GT5A	34CH	TSSOP−8	I = Industrial (−40°C to +85°C)	NiPdAu	Tape & Reel, 5,000 Units / Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

14. All packages are RoHS−compliant (Lead−free, Halogen−free)
15. The standard lead finish is NiPdAu.
16. **For Gresham ONLY die, please order the OPNs: CAT34C02YI−GT5A, CAT34C02VP2IGT4A, CAT34C02HU3IGT4A, CAT34C02HU4IGT4A or CAT34C02HU4IGTU5.**
17. For additional package and temperature options, please contact your nearest **onsemi** Sales office.

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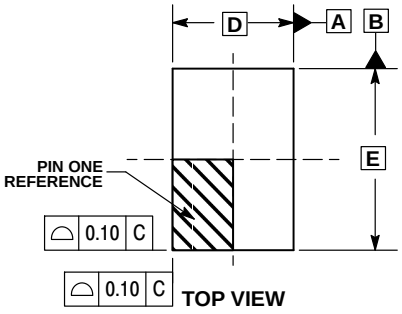
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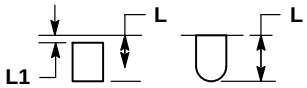


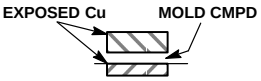
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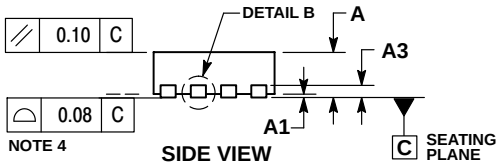
TDFN8, 2x3, 0.5P
CASE 511AK
ISSUE B

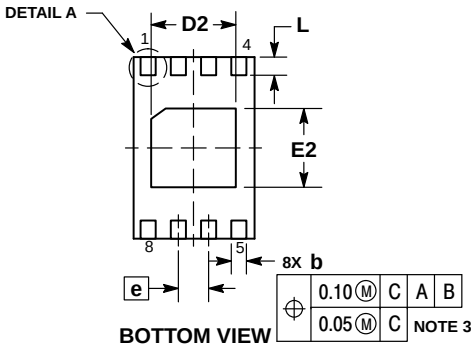
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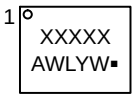




NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20 REF	
b	0.20	0.30
D	2.00 BSC	
D2	1.30	1.50
E	3.00 BSC	
E2	1.20	1.40
e	0.50 BSC	
L	0.20	0.40
L1	–––	0.15

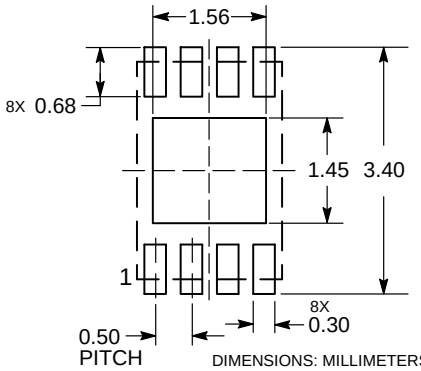
GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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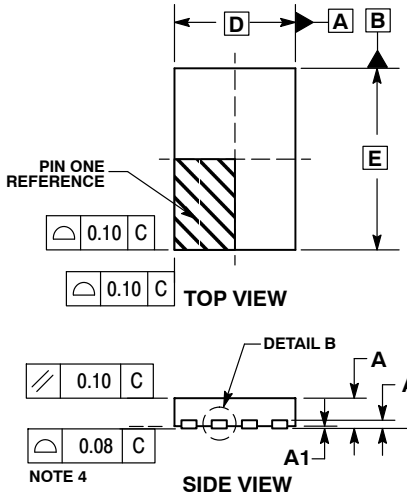
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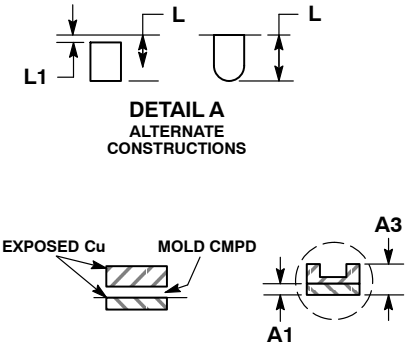


SCALE 2:1

UDFN8, 2x3 EXTENDED PAD
CASE 517AZ
ISSUE A

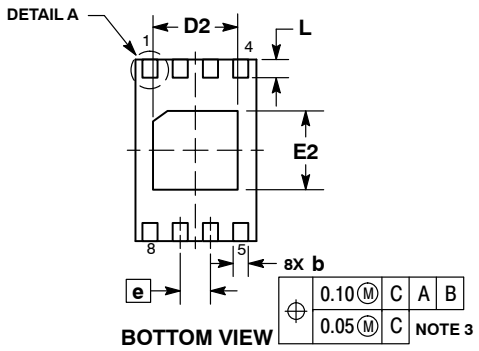
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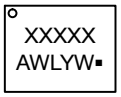


NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.20	0.30
D	2.00 BSC	
D2	1.35	1.45
E	3.00 BSC	
E2	1.25	1.35
e	0.50 BSC	
L	0.25	0.35
L1	---	0.15



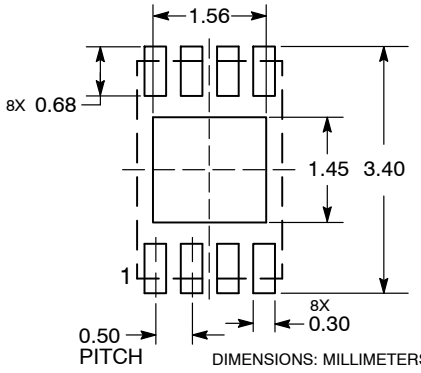
GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*

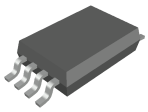


*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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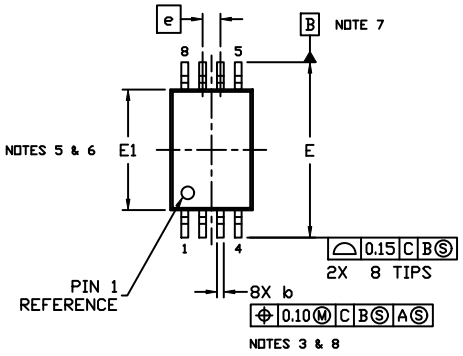
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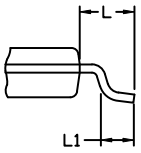


TSSOP8, 4.4x3.0, 0.65P
CASE 948AL
ISSUE A

DATE 20 MAY 2022



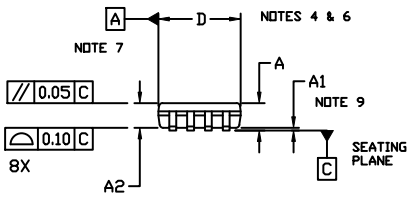
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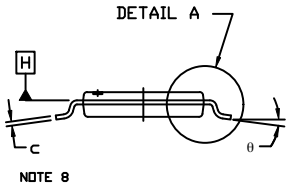
DETAIL A

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5, 2009..
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL NOT BE 0.15 IN EXCESS OF MAXIMUM MATERIAL CONDITION.
4. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.
5. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. DIMENSIONS D AND E1 ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AT DATUM PLANE H.
7. DATUMS A AND B ARE TO BE DETERMINED AT DATUM H.
8. DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 FROM THE LEAD TIP..
9. A1 IS DEFINED AS THE LOWEST VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY..



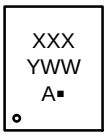
SIDE VIEW



END VIEW

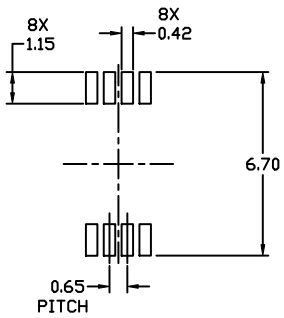
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	1.20
A1	0.05	---	0.15
A2	0.80	0.90	1.05
b	0.19	---	0.30
c	0.09	---	0.20
D	2.90	3.00	3.10
E	6.30	6.40	6.50
E1	4.30	4.40	4.50
e	0.65 BSC		
L	1.00 REF		
L1	0.50	0.60	0.70
θ	0°	---	8°

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
Y = Year
WW = Work Week
A = Assembly Location
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED
MOUNTING FOOTPRINT*

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